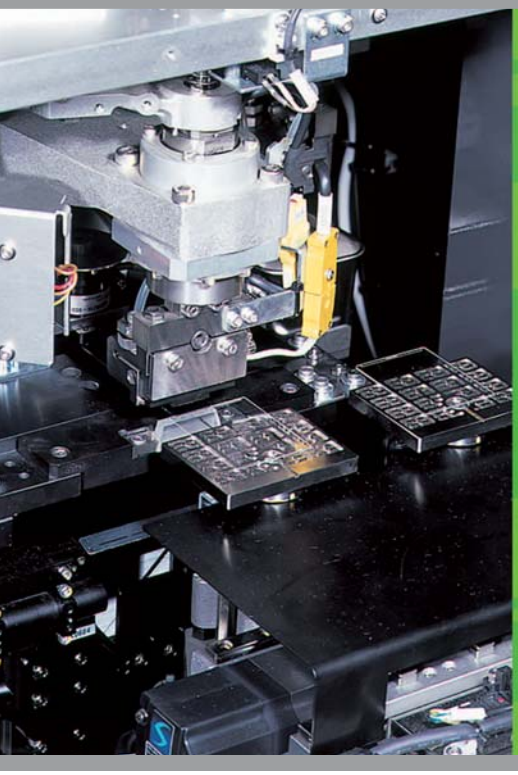
Panasonic
ideas for life

2008

LCD Module Bonder catalog

BONDER FOR FPD



● Industry's First Plug in Idea. Flexibly Supporting A Wide Variety of Liquid Crystal Bonding Methods

Model ID		TBX						
Model No.		KXF-327D						
Selection Option		Double stage			Single stage			
Process		ACF attachment	Pre-bonding	Final bonding	ACF attachment	Pre-bonding	Final bonding	
Bonding Side		Max.2 sides [Adjoining sides] *1			Max.4 sides [Adjoining sides] *2			
Cycle Time		4.5 s/panel *3			It varies depending on some conditions, such as bonding.			
Bonding Accuracy [COG](3σ)		X:±200 µm Y:±100 µm	——	X:±5 µm Y:±5 µm	X:±200 µm Y:±100 µm	——	X:±5 µm Y:±5 µm	
Substrate Dimensions	Panel Dimensions	L 25 mm X W 20 mm to L 78 mm X W 58 mm			L 25 mm X W 20 mm to L 98 mm X W 74 mm *4 L 25 mm X W 20 mm to L 212 mm X W 160 mm *5			
Component Feeding Dimensions	Chip Dimensions TCP/FPC Dimensions	L 6.0 mm X W 0.9 mm to L 20 mm X W 5 mm for COG L 15 mm X W 5 mm to L 61 mm X W 70 mm for FOG						
ACF Width		Width 1.0 mm to 6.5 mm, Diameter of a reel: Max.ø 160 mm						
Feeding Method		Cassette system (2/3–layer tape)	Tray magazine Tray stack	——	Cassette system (2/3–layer tape)	Tray magazine Tray stack	——	
Press Specification	Setting Temperature Max. Pressure	Max.150˚C 180 N/ACF	Max.120˚C 10 N/chip	Max.350˚C 200 N/chip	Max.150˚C 200 N/ACF	Max.120˚C 10 N/chip	Max.350˚C 200 N/chip	
Power Source		3-phase AC 200 V,50/60 Hz ±5 %, 5.2 kVA						
Pneumatic Source		0.49 MPa, 240 L/min (A.N.R.)						
Dimensions		W 2 580 mm X D 967 mm X H 1 700 mm *6						
Mass		2 050 kg*6			2 000 kg*6			

*Please refer to the specifications on details.
*Values such as cycle time and accuracy may vary depending on operating conditions.

*1: In double-panel transport, more than one chip can be bonded.
*2: In single-panel transport, more than one chip can be bonded.
*3: In chip-per-side bonding and double-panel transport
*4: In double-panel transport
*5: In single transport, maximum dimensions including the bonded components
*6: However, main body only

Model ID TBX
Model No. KXF-327D

Model ID **TBX**
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Our Solutions, Your Value

Strong Point of TBX

❶Flexible Machine for Bonding Process
Thanks to the industry's first PLUG IN idea, the component feeding units can be attached, detached, or exchanged without restraint. Also, the peripherals can be connected on site.

❷Quick Model Change
Through all-in-one control by one CPU, overlapping input items are eliminated and the changeover time becomes 1/2 to 1/3 as short as that in our competitor's machine.

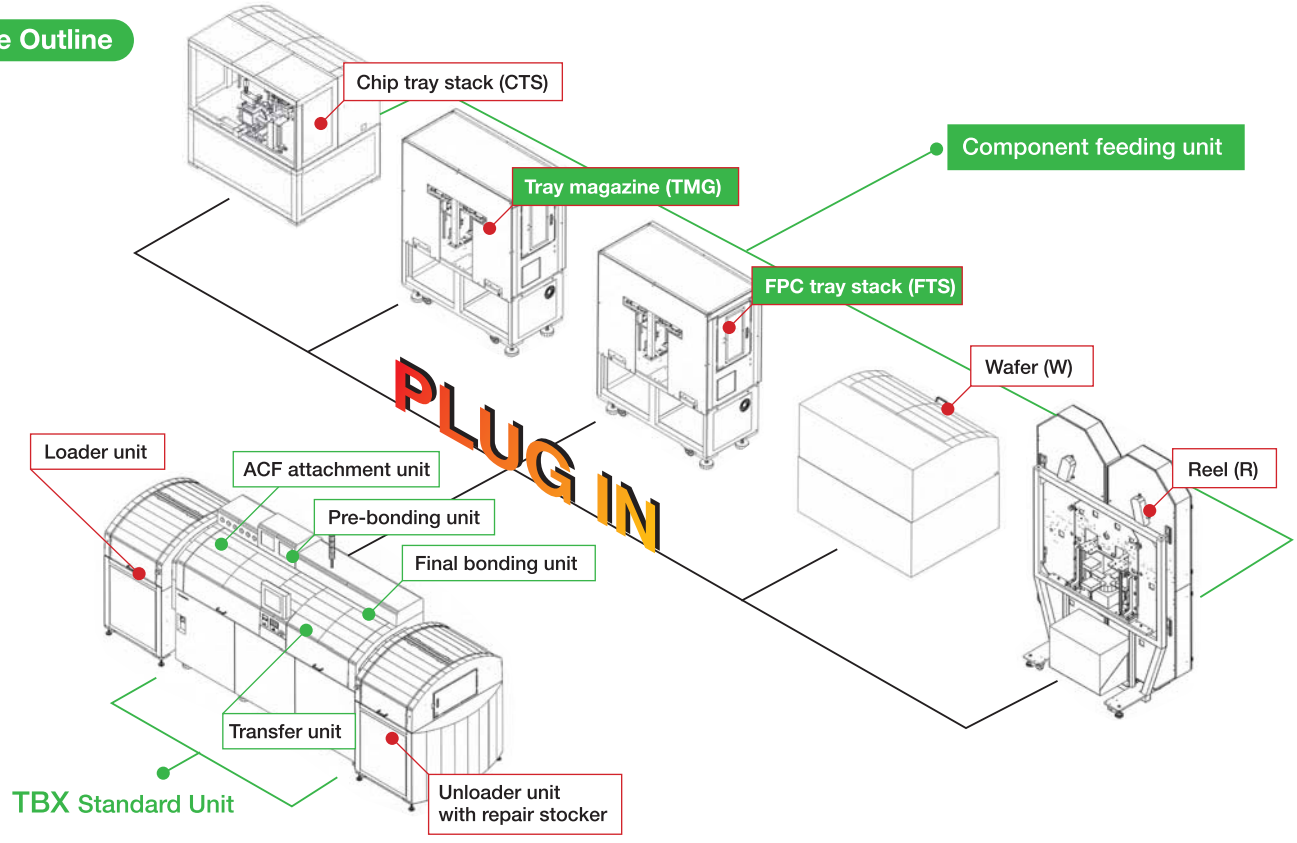
❸High Speed Bonding
Through double-ACF attachment and high-speed rotary pre-bonding head, a 30 % speed up is achieved as compared with our conventional machine.

❹High Accurate Bonding
High-precision bonding is achieved through the adoption of the simultaneous recognition by the double-field-of-view camera, rack-and-pinion θ-table, and high-rigid frame.

❺High Efficiency
Downtime can be reduced through the use of the ACF cassette, sheet-feeding cassette, and repair stocker.

Flexible Machine for Bonding Process

Machine Outline



eco ideas
- GHG Factor 1.91
- Resource Factor 2.23 (Ref.Product: FB50)

eco ideas Matsushita Group products are built with the environment in mind.
http://panasonic.co.jp/eco/en/

ISO 14001 Matsushita group builds Environmental Management System in the factories of the world and acquires the International Environmental Standard ISO 14001:2004.

⚠Safety Cautions To ensure safety when using this equipment all work should be performed according to that as stated in the supplied Operating Instructions. Read your operating instructions manual thoroughly.

Inquiries...

DJK DAIICHI JITSUGYO CO., LTD.

DJK Global Network
Tokyo / Osaka / Nagoya / Tohoku / Hiroshima / Fukuoka / Sapporo
Shanghai / Tianjin / Dalian / Shenzhen / Guangzhou / Hong Kong / Seoul / Taipei
Singapore / Kuala Lumpur / Bangkok / Manila / Jakarta / Hanoi / Ho Chi Minh City / New Delhi
Chicago / Houston / San Diego / Knoxville / Phoenix / Puerto Rico / Tijuana / Sao Paulo
London / Frankfurt / Praha / Budapest / Warsaw

Panasonic Factory Solutions Co., Ltd.
Marketing & Solution Division
2-7 Matsuba-cho, Kadoma City, Osaka 571-8502, Japan
TEL +81-6-6905-4396 / FAX +81-6-905-5145
http://panasonic.co.jp/pfsc/en/

All data as of December. 1, 2007.